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(54) **ADAPTIVE FLIP CHIP BONDING FOR SEMICONDUCTOR PACKAGES**

(71) Applicant: **Infineon Technologies AG**, Neubiberg (DE)

(72) Inventors: **Chew Yeek Lau**, Muar (MY); **Swee Kah Lee**, Melaka (MY); **Fong Mei Lum**, Melaka (MY); **Kon Hoe Chin**, Pusing (MY)

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ABSTRACT

A method of forming one or more semiconductor packages includes mounting one or more semiconductor dies on the metal strip such that the one or more semiconductor dies are in a flip chip arrangement whereby terminals of the one or more semiconductor dies face the upper surface of the metal strip, forming an electrically insulating encapsulant material on the upper surface of the metal strip that encapsulates the one or more semiconductor dies, and forming package terminals that are electrically connected with the terminals of the one or more semiconductor dies, wherein the package terminals are formed from the metal strip or from metal that is deposited after removing the metal strip.

